



Description

The Si2392ADS-T1-GE3 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 100V$ $I_D = 5A$

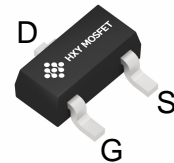
$R_{DS(ON)} < 125m\Omega$ @ $V_{GS}=10V$

Application

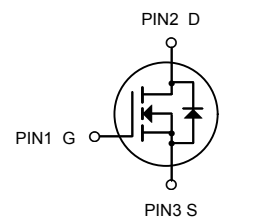
Battery protection

Load switch

Uninterruptible power supply



SOT-23



N-Channel MOSFET

Package Marking and Ordering Information

| Product ID | Pack | Brand | Qty(PCS) |
|------------------|--------|------------|----------|
| Si2392ADS-T1-GE3 | SOT-23 | HXY MOSFET | 3000 |

Absolute Maximum Ratings ($T_C=25^{\circ}C$ unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|---------------------------|--|------------|---------------|
| V_{DS} | Drain-Source Voltage | 100 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D @ T_A = 25^{\circ}C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 5 | A |
| $I_D @ T_A = 70^{\circ}C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 3.2 | A |
| I_{DM} | Pulsed Drain Current ² | 16 | A |
| $P_D @ T_A = 25^{\circ}C$ | Total Power Dissipation ³ | 3.1 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^{\circ}C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^{\circ}C$ |
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient(steady state) ¹ | 100 | $^{\circ}C/W$ |
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient($t < 10s$) ¹ | 40 | $^{\circ}C/W$ |



Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--------------|--|--|------|------|-----------|------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V$, $I_D=250\mu A$ | 100 | 108 | --- | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=10V$, $I_D=4A$ | --- | 110 | 125 | m Ω |
| | | $V_{GS}=4.5V$, $I_D=2A$ | --- | 120 | 145 | m Ω |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}$, $I_D=250\mu A$ | 1.2 | 1.7 | 2.5 | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=80V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1 | μA |
| | | $V_{DS}=80V$, $V_{GS}=0V$, $T_J=85^{\circ}\text{C}$ | --- | --- | 50 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V$, $V_{DS}=0V$ | --- | --- | ± 100 | nA |
| R_g | Gate Resistance | $V_{DS}=0V$, $V_{GS}=0V$, $f=1\text{MHz}$ | --- | 2.3 | 4.6 | |
| Q_g | Total Gate Charge (10V) | $V_{DS}=30V$, $V_{GS}=10V$, $I_D=4A$ | --- | 3.57 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 0.76 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 0.71 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}=30V$, $V_{GS}=10V$, $R_G=3.3$ $I_D=1A$ | --- | 11 | --- | ns |
| T_r | Rise Time | | --- | 6 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 30 | --- | |
| T_f | Fall Time | | --- | 4 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=50V$, $V_{GS}=0V$, $f=1\text{MHz}$ | --- | 182 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 30 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 3.6 | --- | |
| I_S | Continuous Source Current ^{1,4} | $V_G=V_D=0V$, Force Current | --- | --- | 2 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V$, $I_S=1A$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1.2 | V |

Note :

1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

3.The power dissipation is limited by 150°C junction temperature

4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

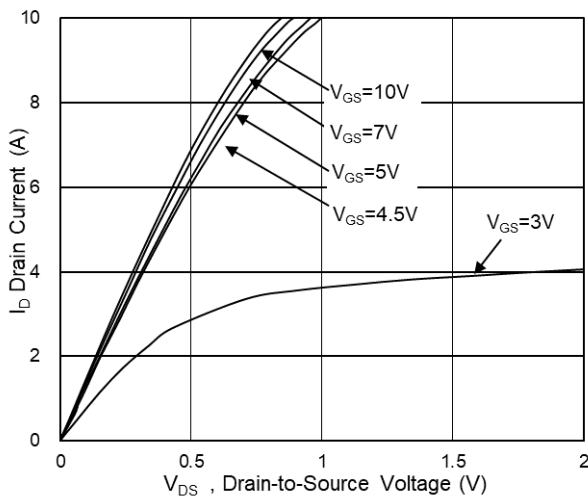


Fig.1 Typical Output Characteristics

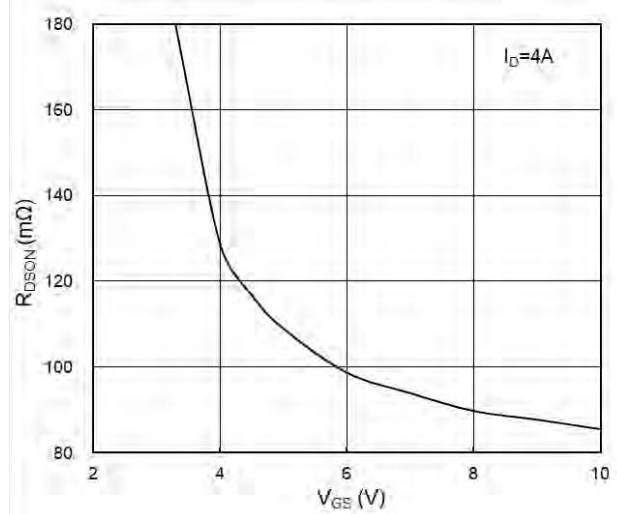


Fig.2 On-Resistance vs G-S Voltage

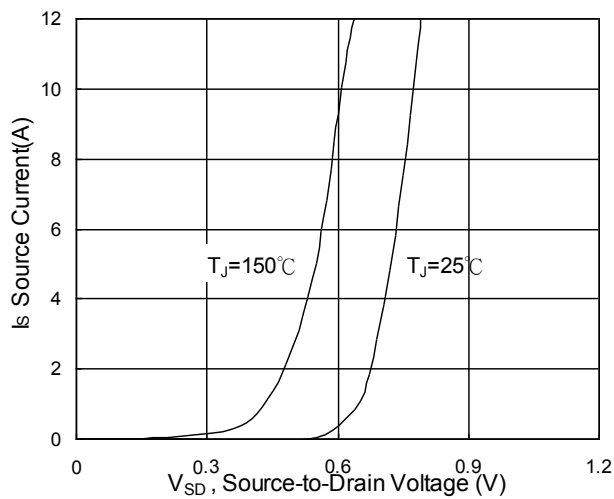


Fig.3 Source Drain Forward Characteristics

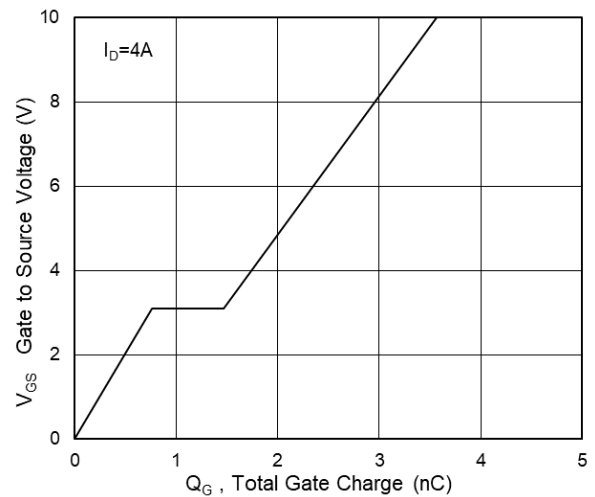


Fig.4 Gate-Charge Characteristics

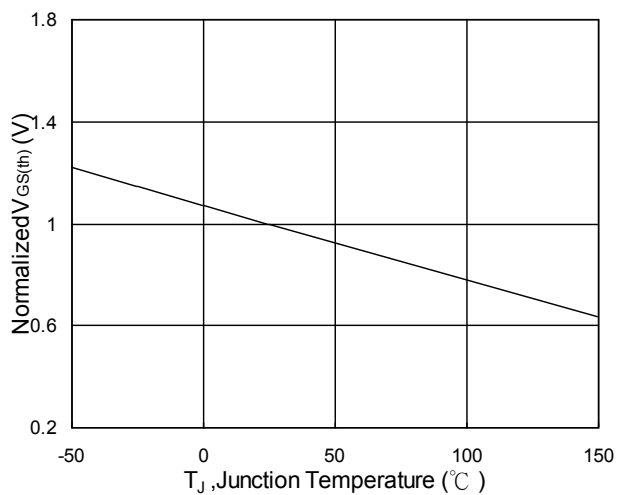


Fig.5 Normalized $V_{GS(th)}$ vs T_J

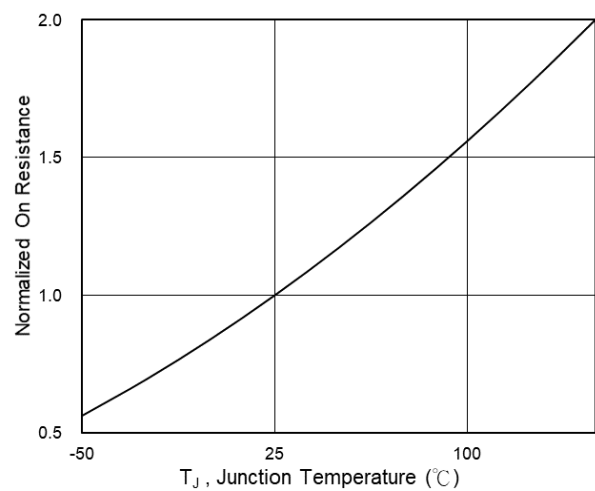


Fig.6 Normalized $R_{DS(on)}$ vs T_J

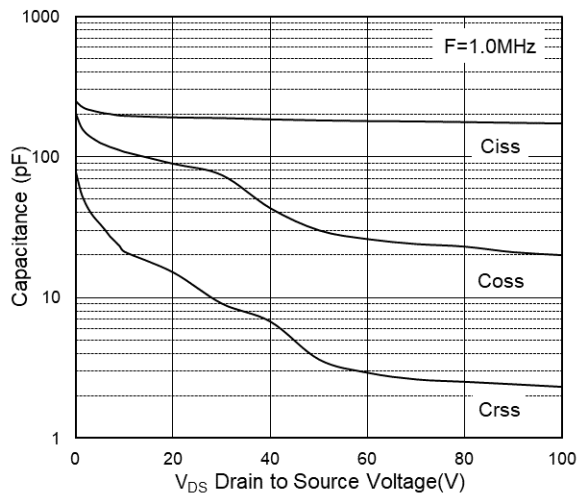


Fig.7 Capacitance

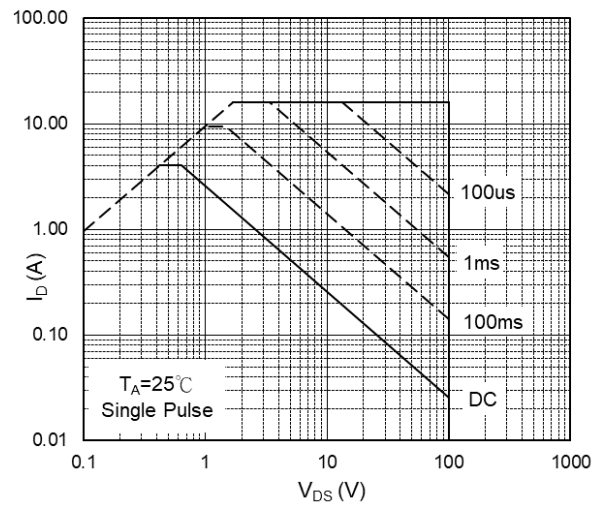


Fig.8 Safe Operating Area

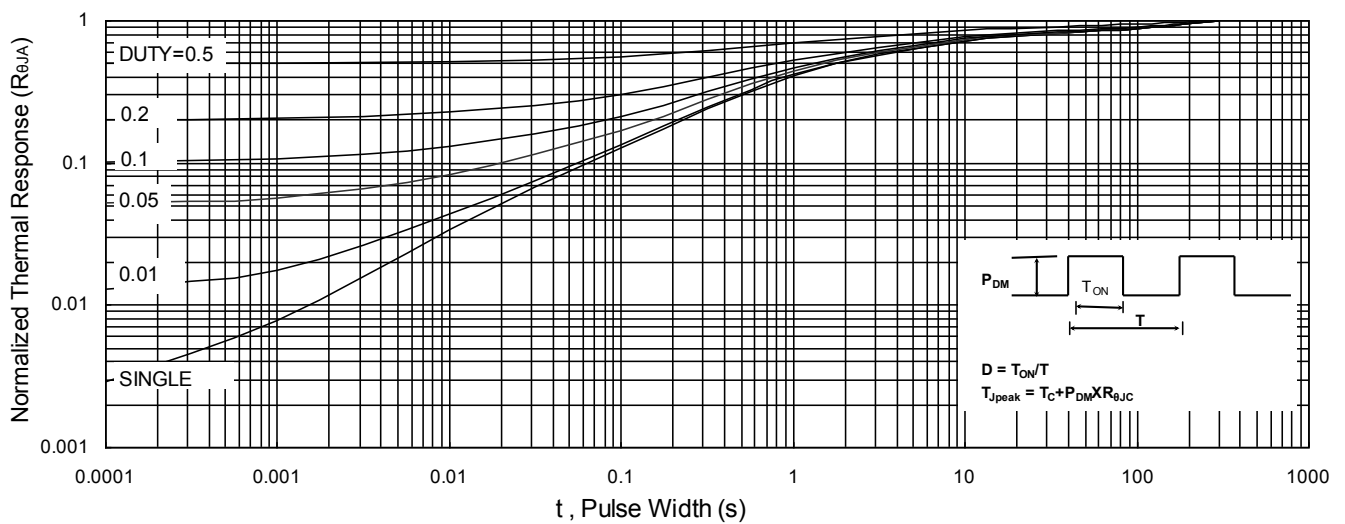


Fig.9 Normalized Maximum Transient Thermal Impedance

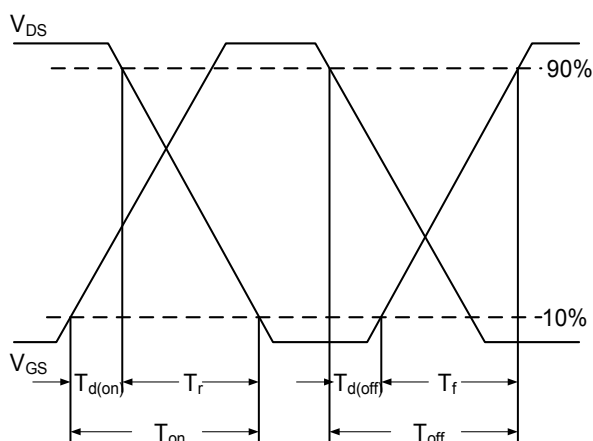


Fig.10 Switching Time Waveform

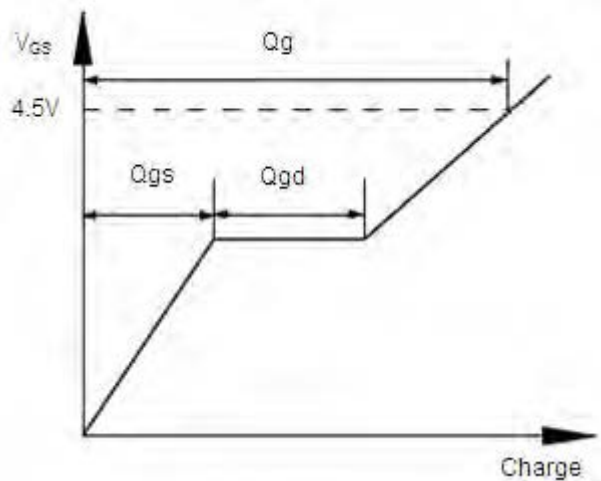
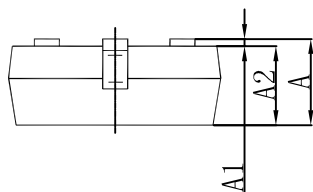
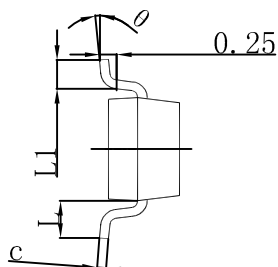
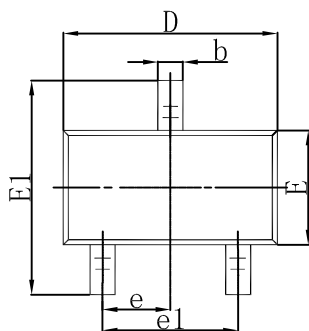


Fig.11 Gate Charge Waveform

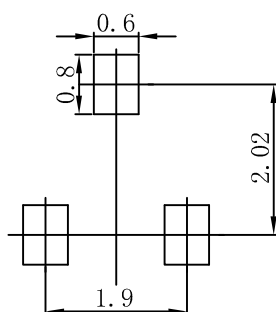


SOT-23 Package Outline Dimensions



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 0.900 | 1.150 | 0.035 | 0.045 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 0.900 | 1.050 | 0.035 | 0.041 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.080 | 0.150 | 0.003 | 0.006 |
| D | 2.800 | 3.000 | 0.110 | 0.118 |
| E | 1.200 | 1.400 | 0.047 | 0.055 |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 |
| e | 0.950 TYP | | 0.037 TYP | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.550 REF | | 0.022 REF | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 |
| θ | 0° | 8° | 0° | 8° |

SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.



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